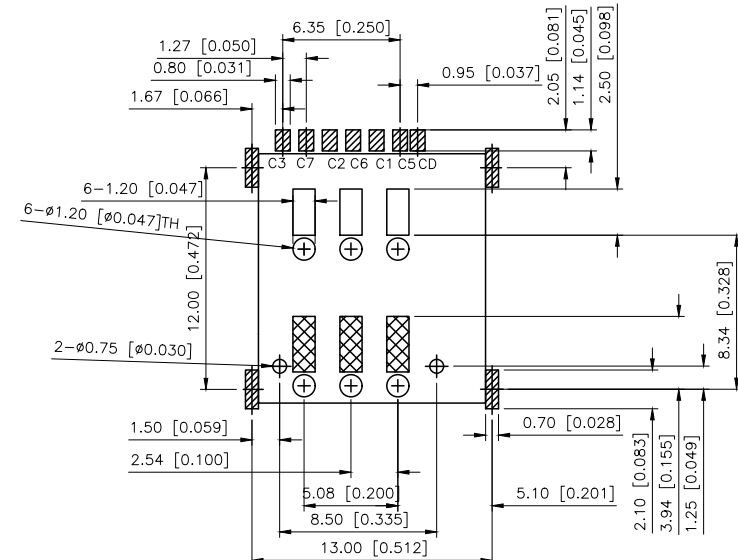
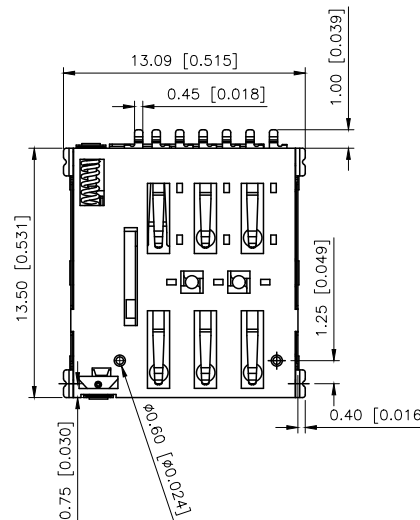
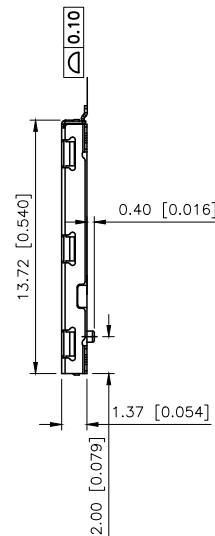
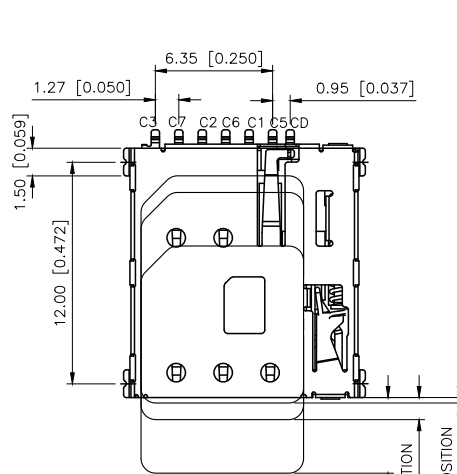
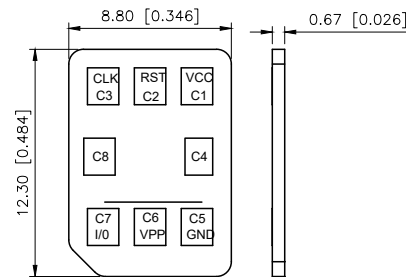
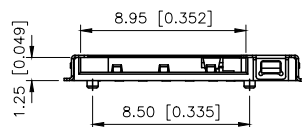


REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.07	阿树



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

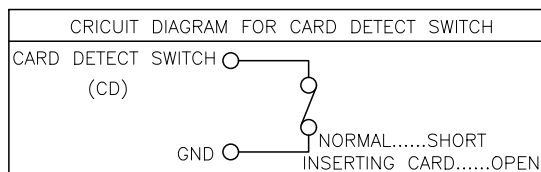


4FF SIM CARD

1. MATERIAL:
HOUSING: HI-TEMP. PLASIC UL 94V-0
TERMINAL: COPPER ALLOY
SHELL: SUS
2. PLATING:
TERMINAL:
CONTACT AREA: Au GOLD FLASH.
SOLDER AREA: Au GOLD FLASH.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.
3. SPECIALITY:
3.1 Rated current: 1.0A
3.2 Rated voltage: 30V
3.3 Contact Resistance: 100mΩ MAX
3.4 Insulation Resistance: 1000MΩ MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability: 260±0/-5°C. 30±10s.
3.7 Durability: 5000 Cycles Min.
3.8 Operating condition: Temperature -40°C ~ +85°C
Humidity 80% R.H MAX

▨ PAD
▩ KEEP OUT AREA

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



AuGLAR	$\pm 5^\circ$
X.	± 0.40
X.x	± 0.30
X.xx	± 0.20
X.xxx	± 0.15
UNSPECIFIED TOLERANCES	



③	Shell	1	SUS	
②	Terminal	7	COPPER ALLOY	
①	Housing	1	HI-TEMP. PLASIC UL 94V-0	BLACK
ITEM	PAPT NAME	QTY	MATERIAL	FINISHING

DESIGN	阿树	VIEW:	MODEL TYPE: SIM CARD CONN
CHECKED		UNIT: mm/in	PART NO.: XKNANO-113
APPROVED		SIZE: A4	DWG NO.: